Description

TVS diodes are designed to replace multilayer varistors (MLVs) in portable applications such as cell phones, notebook computers, and PDA's. They offer superior electrical characteristics such as lower clamping voltage and no device degradation when compared to MLVs.

The UMD12VL-563 is a TVS array designed to protect I/O or data lines from the damaging effects of ESD. Their integrated design provides very effective and reliable protection for five separate lines using only one package. The SOT-563 is a very small package which allows space saving on high density printed circuit board and also gives the designer the flexibility to provide Uni-Directional or Bi-Directional protection.

Features

- * Solid-state silicon avalanche technology
- * SOT-563 package
- * Uni-Directional or Bi-Directional protection
- * Protects up to five data lines
- * 65 Watts peak pulse power (tp = $8/20\mu s$)
- * Working voltage: 12V
- * Low clamping factor Vcl/Vbr
- * Low leakage current
- * Full RoHS compliance
- * Complies with the following standards:
 - IEC 61000-4-2 (ESD) Air-15kv, Contact-8kv
 - IEC 61000-4-4 (EFT) (5/50ns)
 - IEC 61000-4-5 (Surge) (8/20μs)

Small Surface Mount Device TVS



SOT-563 Pin Configuration



<u>Pin</u>	Description
1	Cathode
2	Anode
3	Cathode
4	Cathode
5	Cathode
6	Cathode

Mechanical Characteristics

- * Molded SOT-563 package
- * Weight 3 milligrams (Approximate)
- * Available in Lead-Free Pure-Tin Plating
- * Solder Reflow Temp: Pure-Tin (Sn), 260-270°C
- * Consult Factory for Leaded Device Availability
- * Flammability Rating UL 94V-0
- * 8mm Tape and Reel per EIA Standard 481
- * Device Marking: Marking Code,

Pin one defined by DOT

Applications

- * Cellular Handset
- * PDA
- * Notebook
- * Digital Camera
- * Wifi Phone
- * Microprocessor Based Equipment

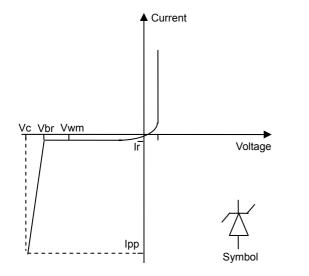


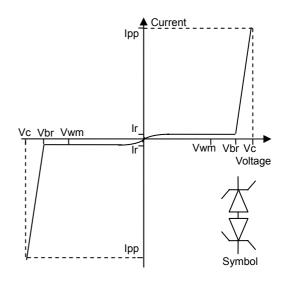
Absolute Maximum Ratings @ 25°C unless otherwise specified					
Parameter	Symbol	Value	Units		
Peak Pulse Power; pulse waveform = 8/20μs	Ppp	65	W		
Peak Pulse Current; pulse waveform = 8/20μs	Ipp	3	A		
ESD per IEC 61000-4-2 (Air)	Van	±15	kV		
ESD per IEC 61000-4-2 (Contact)	Vpp	±8	K V		
Operating Temperature	Tj	-55 to 125	°C		
Storage Temperature	Tstg	-55 to 150	°C		

Electrical Characteristics @ 25°C unless otherwise specified						
Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Stand-off Voltage	Vwm				12.0	V
Breakdown Voltage	Vbr	It=1mA	13.0			V
Leakage Current	Ir	Vwm=9V, T=25°C			0.3	μΑ
Clamping Voltage	Vc	Ipp=1A Tp=8/20μs			16.0	V
Clamping Voltage	Vc	Ipp=3A Tp=8/20μs			21.7	V
Peak Pulse Current	Ipp	Tp=8/20μs			3	A
Junction Capacitance	Cj	Vr=0V, f=1MHz		7.0	8.5	pF

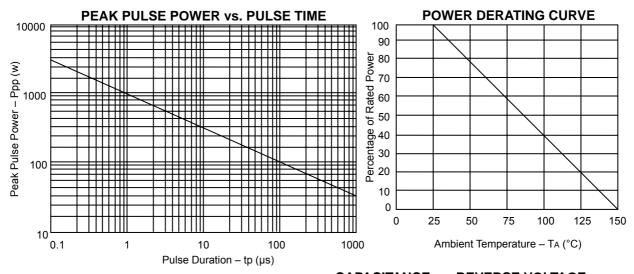
Uni-Directional Protection

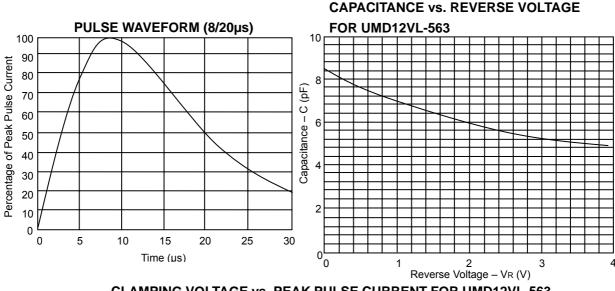
Bi-Directional Protection

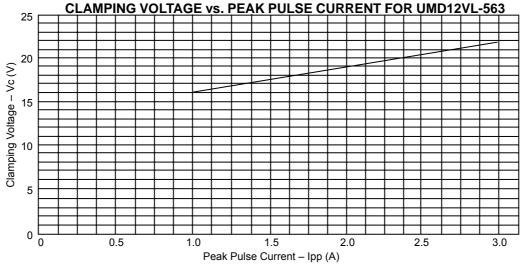




Electrical Characteristics Graphs







Applications Information

The UMD12VL-563 is designed for use in applications where board space is at a premium. Each device requires less than 3mm² of PCB area and will protect up to five Uni-Directional lines.

The UMD12VL-563 provides up to 5 lines of protection in a common-mode Uni-Directional configuration.

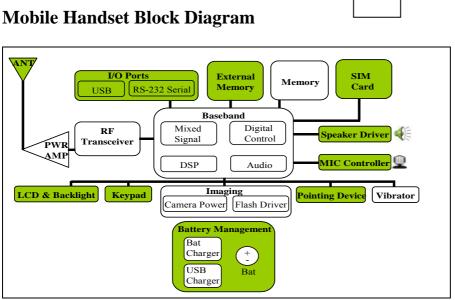
Circuit connectivity is as follows:

- Line 1 is connected to Pin 1
- Line 2 is connected to Pin 6
- Line 3 is connected to Pin 3
- Line 4 is connected to Pin 4
- Line 5 is connected to Pin 5
- Pin 2 is connected to ground

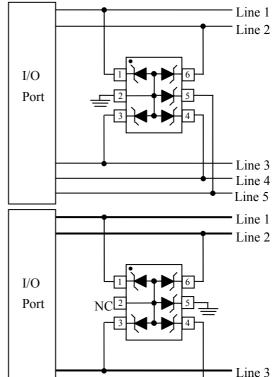
The UMD12VL-563 provides up to 4 lines of protection in a common-mode Bi-Directional configuration.

Circuit connectivity is as follows:

- Line 1 is connected to Pin 1
- Line 2 is connected to Pin 6
- Line 3 is connected to Pin 3
- Line 4 is connected to Pin 4
- Pin 2 is not connected
- Pin 5 is connected to ground

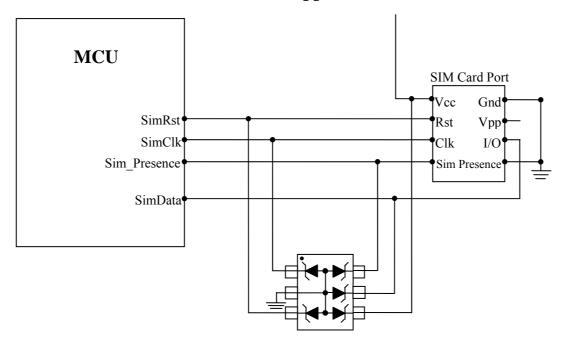


Areas that require ESD protection are highlighted.

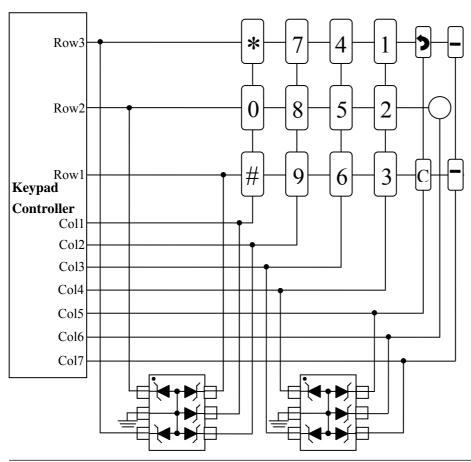


Line 4

UMD12VL-563 on Sim Card Port Application

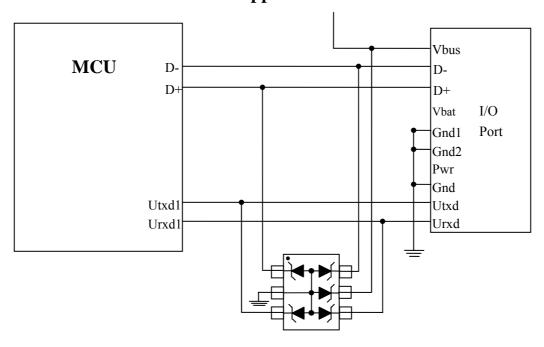


UMD12VL-563 on Keypad Application

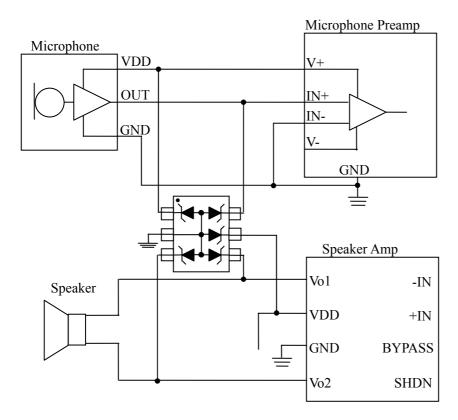


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UMD12VL-563 on I/O Port Application

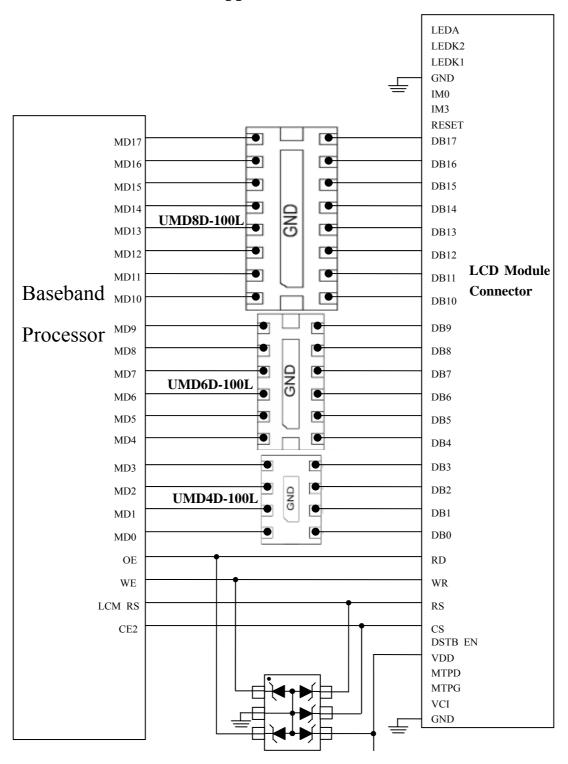


UMD12VL-563 on Speaker and Microphone Application



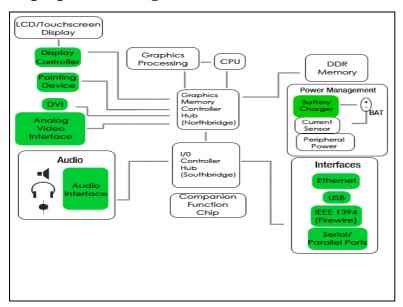
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UMD12VL-563 on LCM Application



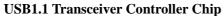
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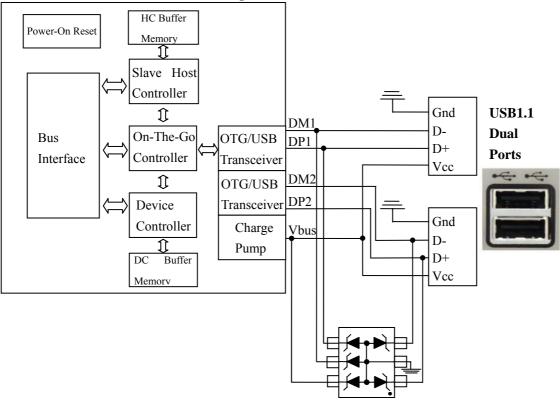
Laptop Block Diagram



Areas that require ESD protection are highlighted.

UMD12VL-563 on Dual USB1.1 Ports Protection





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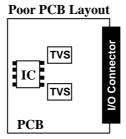
Circuit Board Layout Recommendations

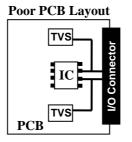
Good circuit board layout is critical for creating an effective surge suppression circuit. The following PCB guidelines are recommended to enhance the performance of a TVS device:

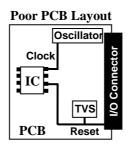
- Place the TVS near the input terminals or connectors to restrict transient coupling.
- Minimize the path length between the TVS and the protected line.
- The ESD transient return path to ground should be kept as short as possible.
- Place a TVS and decoupling capacitor between power and ground of components that may be vulnerable to electrostatic discharges to the ground plane.
- Minimize all conductive loops including power and ground loops.
- Use multilayer boards when possible.
- Minimize interconnecting line lengths.
- Never run critical signals near board edges.
- Fill unused portions of the PCB with ground plane.

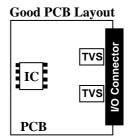
Matte Tin Lead Finish

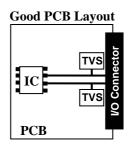
Matte tin has become the industry standard lead-free replacement for SnPb lead finishes. A matte tin finish is composed of 100% tin solder with large grains. Since the solder volume on the leads is small compared to the solder paste volume that is placed on the land pattern of the PCB, the reflow profile will be determined by the requirements of the solder paste. Therefore, these devices are compatible with both lead-free and SnPb assembly techniques. Unlike other lead-free compositions, matte tin does not have any added alloys that can cause degradation to solder joint.

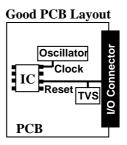








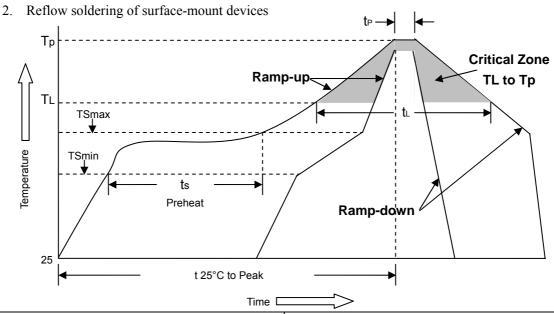




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Soldering Method for UMD's Products

1. Storage environment: Temperature = 10°C~35°C Humidity = 65%±15%



Profile Feature	Pb-Free Assembly		
Average ramp-up rate (TL to TP)	<3°C/sec		
Preheat			
- Temperature Min (TSmin)	150°C		
- Temperature Max (Tsmax)	200°C		
- Time (min to max) (ts)	60~180sec		
TSmax to TL			
- Ramp-up Rate	<3°C/sec		
Time maintained above:			
- Temperature (TL)	220°C		
- Time (t _L)	50~145sec		
Peak Temperature (Tp)	260°C +0/-5°C		
Time within 5°C of actual Peak	20, 40		
Temperature (tp)	20~40sec		
Ramp-down Rate	<6°C/sec		
Time 25°C to peak Temperature	<8 minutes		

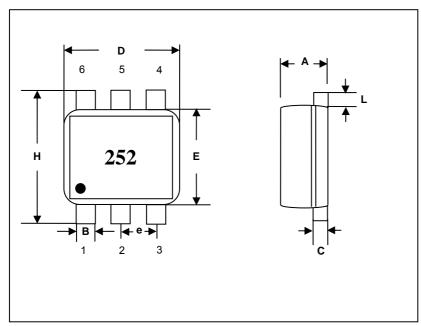
Flow (wave) soldering (solder dipping)

Products	Dipping time	
Pb devices	5sec±1sec	
Pb-Free devices	5sec±1sec	

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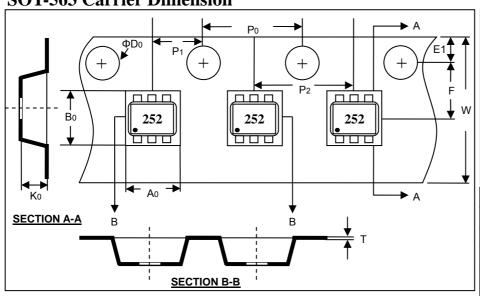


SOT-563 Dimension Drawing

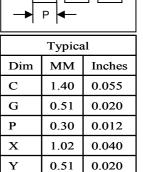


Dimensions					
Dim	Inch	nes	mm		
Dilli	Min	Max	Min	Max	
A	0.020	0.024	0.50	0.60	
Н	0.059	0.067	1.50	1.70	
В	0.007	0.011	0.17	0.27	
D	0.059	0.067	1.50	1.70	
Е	0.043	0.051	1.10	1.30	
e	0.020 BSC		0. 50	BSC	
L	0.004	0.012	0.10	0.30	
С	0.003	0.006	0.08	0.16	

SOT-563 Carrier Dimension



Mounting Pattern



Dimensions in mm.

Reel Dia.	Tape Width	A0	В0	K0	ФD0	E1
178mm (7")	8mm	1.78±0.05	1.78±0.05	0.69±0.05	1.50±0.10	1.75±0.10
F	W	P0	P1	P2	T	
3.50±0.05	8.00±0.30	4.00±0.10	2.00±0.05	4.00±0.10	0.20±0.05	

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Marking Code

Part Number	Device Marking
UMD12VL-563	252

Ordering Information

Part Number	Lead Finish	Qty Per Reel	Reel Size
UMD12VL-563	Pb-Free	3,000	7 inch

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